

Statistical Analysis and Optimization of Asynchronous Digital Circuits



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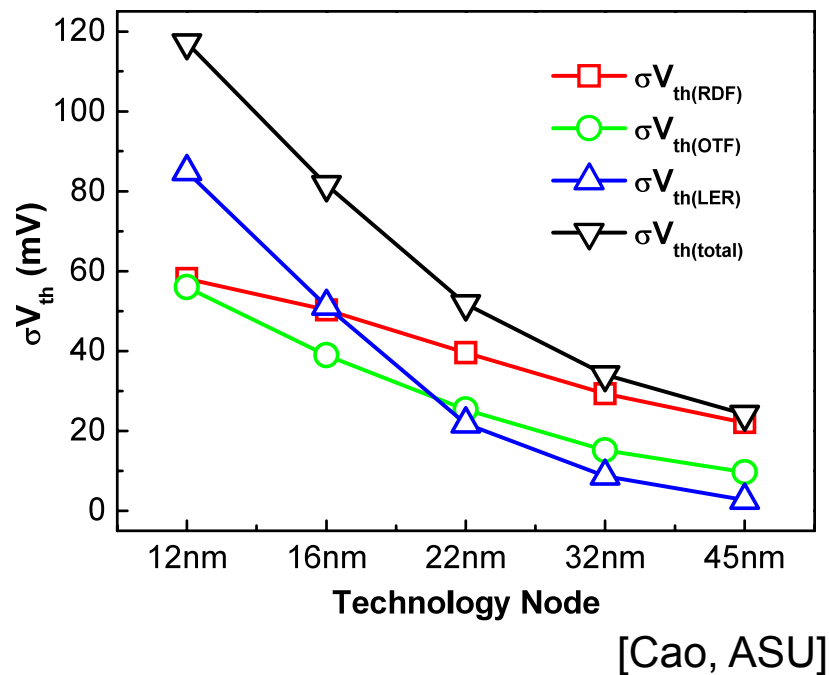
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Outline

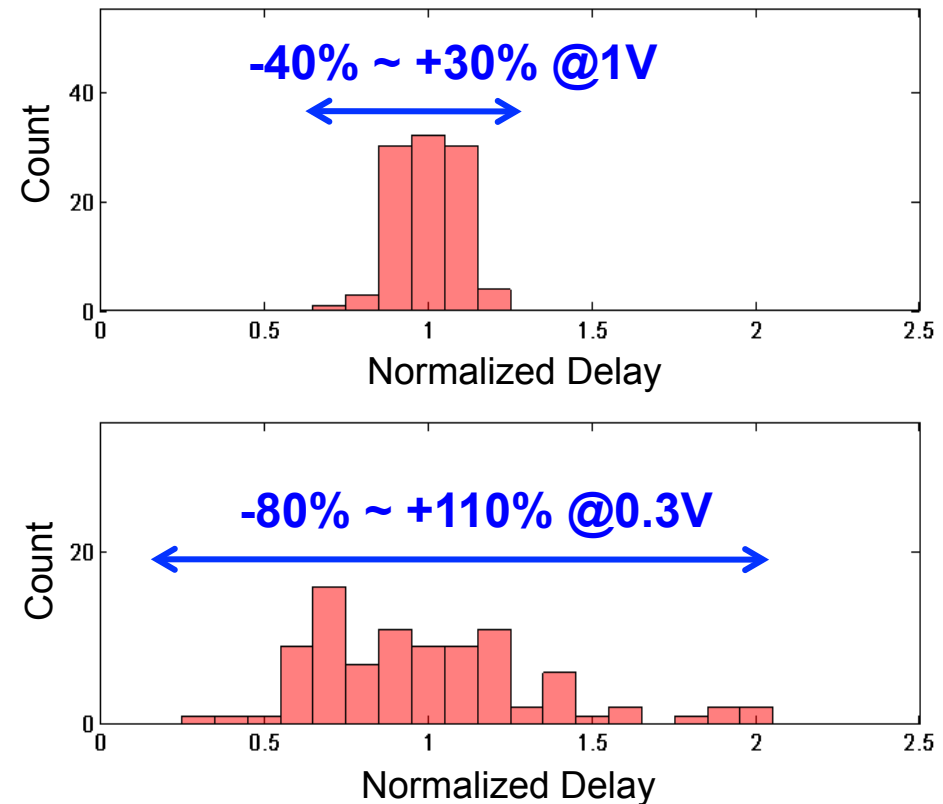
- Motivation
- Variability model of CMOS digital circuit
- Performance model for different timing schemes
- Performance comparison
- Conclusion

Variability Continues to Increase as Technology and Voltage Scales Down

Device variability vs. Technology node

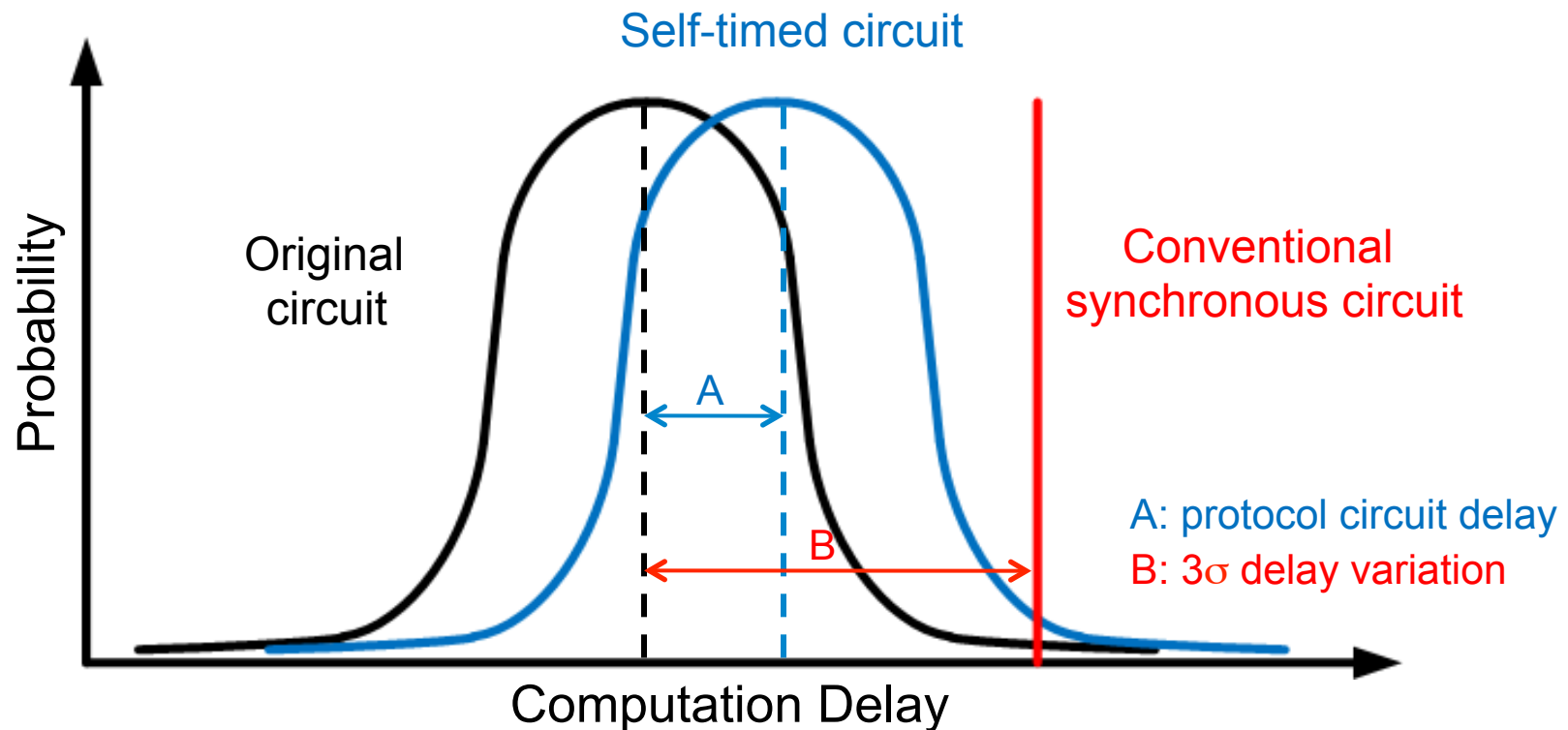


Delay spread due to process variations



- Higher variability with finer design rules and larger wafers
- Higher variability with lower supply voltages

Circuit Performance Characteristics with Different Timing Schemes



- Self-timed circuit is a variation-monitoring circuit by itself
- Becomes advantageous when the variation is large ($B > A$)
- Statistical analysis framework is necessary

Statistical Analysis Framework

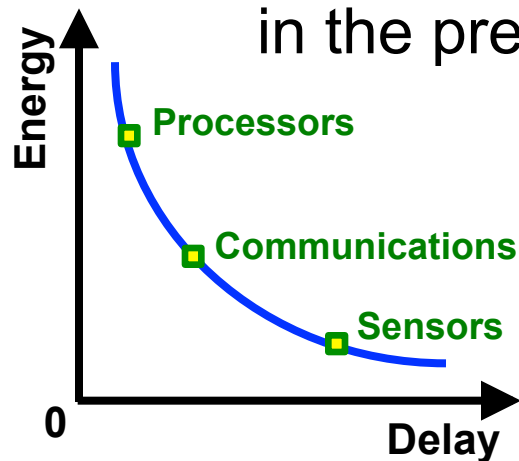
Circuit Variability Model

- Supply voltage
- Logic depth
- Width and length
- Body bias

Performance Model

- Computation overhead
- Communication overhead
- Delay and energy performance

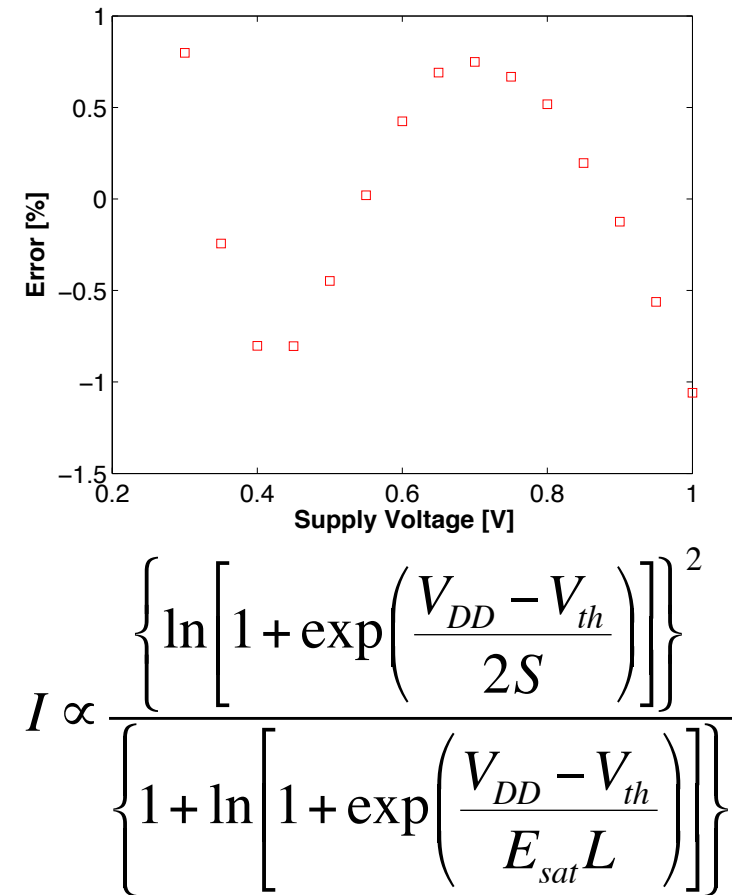
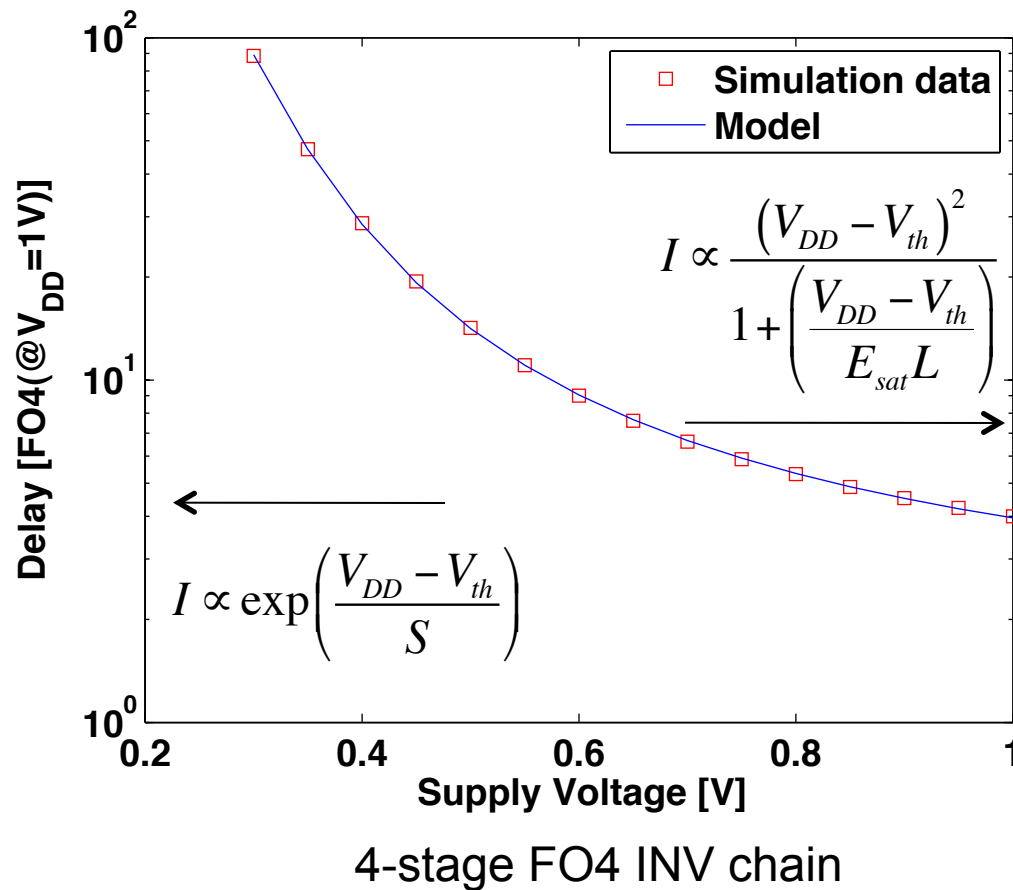
Determine the optimal timing strategy
in the presence of variability



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Delay Model of CMOS Digital Circuit



- One unified current model across different operating regions
- Model error <2% from 0.3V to 1V

Delay Variability Model

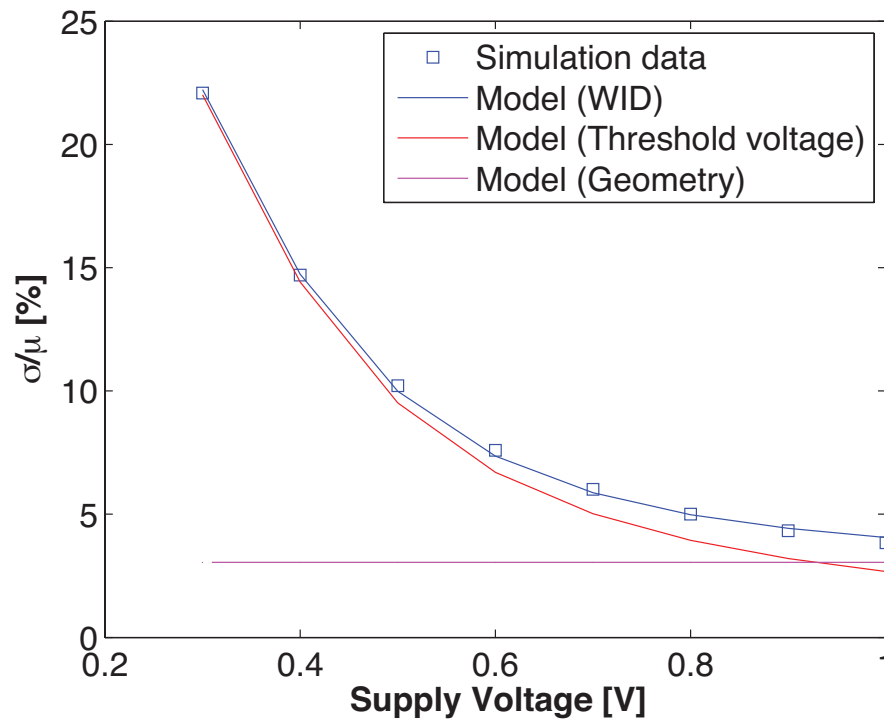
$$\frac{\sigma_{T_d}}{\mu_{T_d}} = \sqrt{\left(S_{T_d}^{V_{th}}\right)^2 \cdot \left(\frac{\sigma_{V_{th}}}{\mu_{V_{th}}}\right)^2 + \left(S_{T_d}^K\right)^2 \cdot \left(\frac{\sigma_K}{\mu_K}\right)^2}$$

$$S_{T_d}^{V_{th}} = \frac{\partial V_{th} / V_{th}}{\partial T_d / T_d}$$

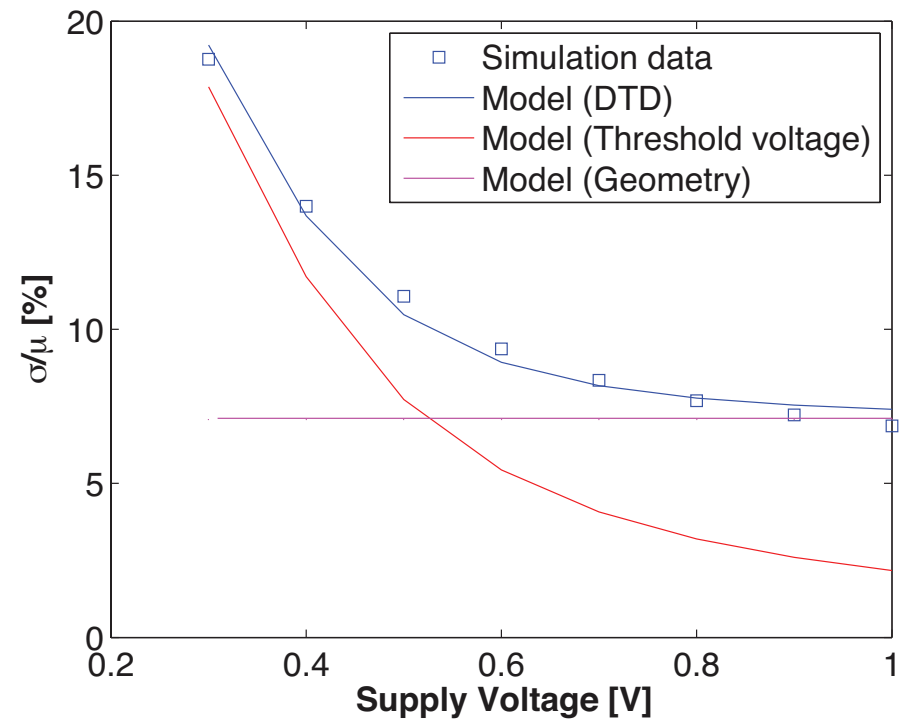
$$S_{T_d}^K = \frac{\partial K / K}{\partial T_d / T_d}$$

Threshold voltage

Geometry

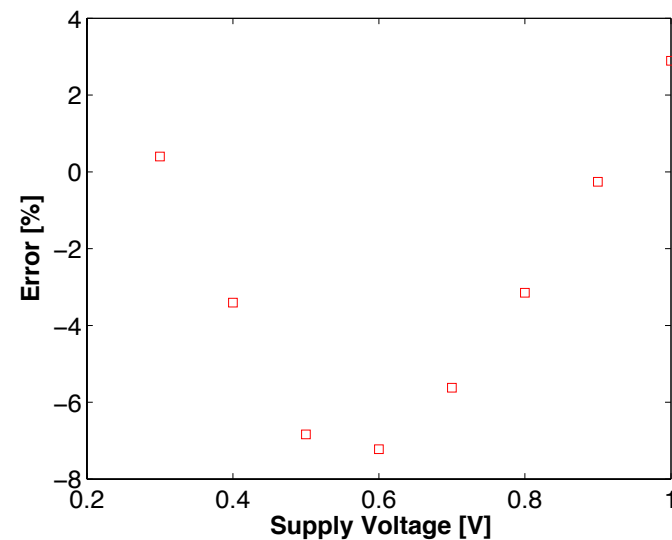
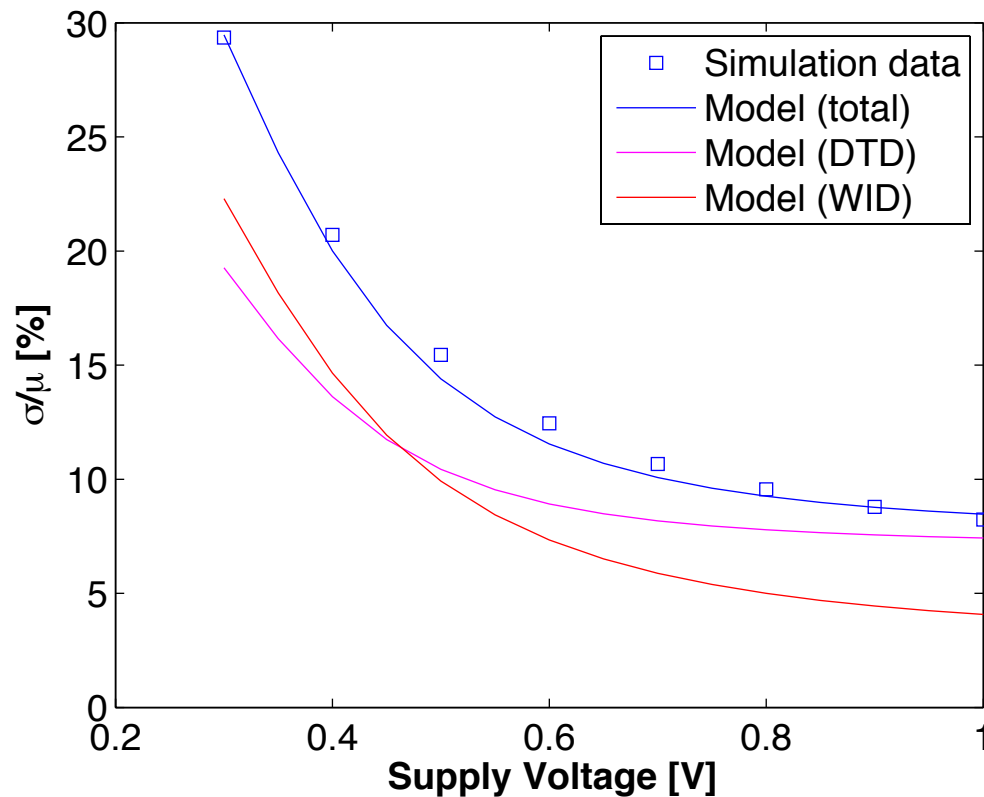


Within die variation (WID)
“Local mismatch”



Die-to-die variation (DTD)
“Global variation”

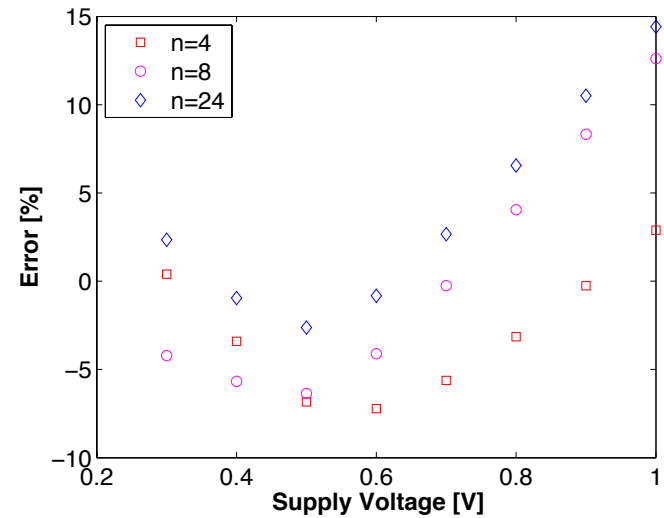
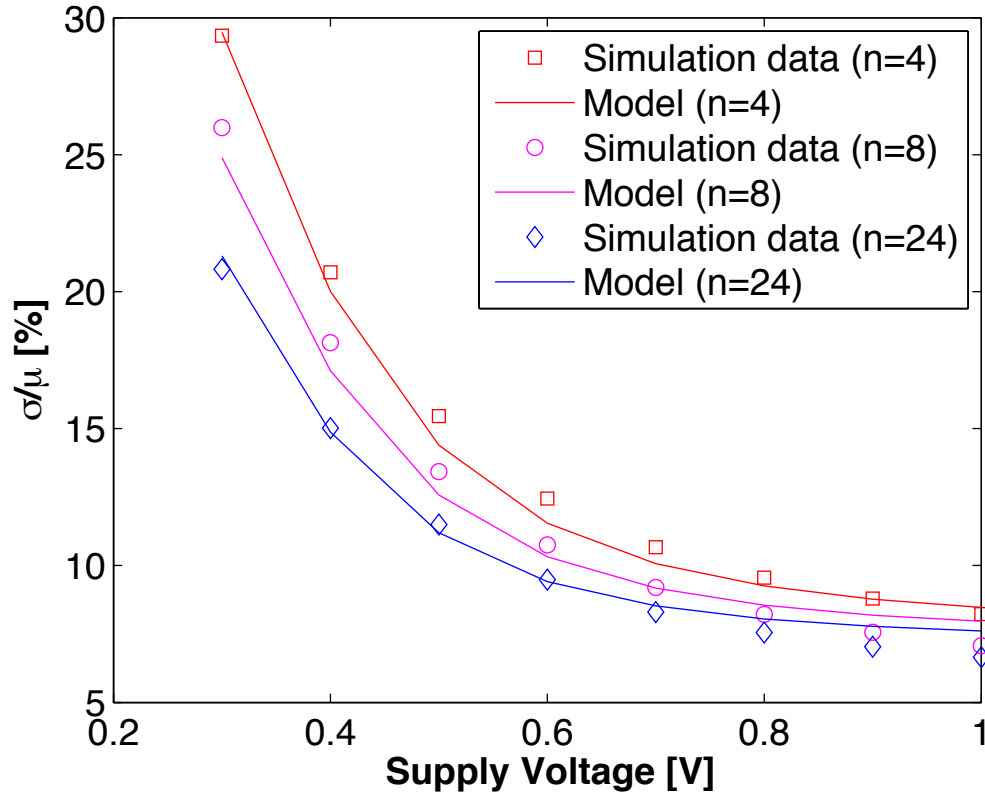
Delay Variability Model



$$\frac{\sigma_{T_{d,total}}}{\mu_{T_{d,total}}} = \sqrt{\left(\frac{\sigma_{T_{d,DTD}}}{\mu_{T_{d,DTD}}}\right)^2 + \left(\frac{\sigma_{T_{d,WID}}}{\mu_{T_{d,WID}}}\right)^2}$$

- Model error <8% from 0.3V to 1V
- Local mismatch dominates at low supply voltages

Delay Variability Model with Different Logic Depths



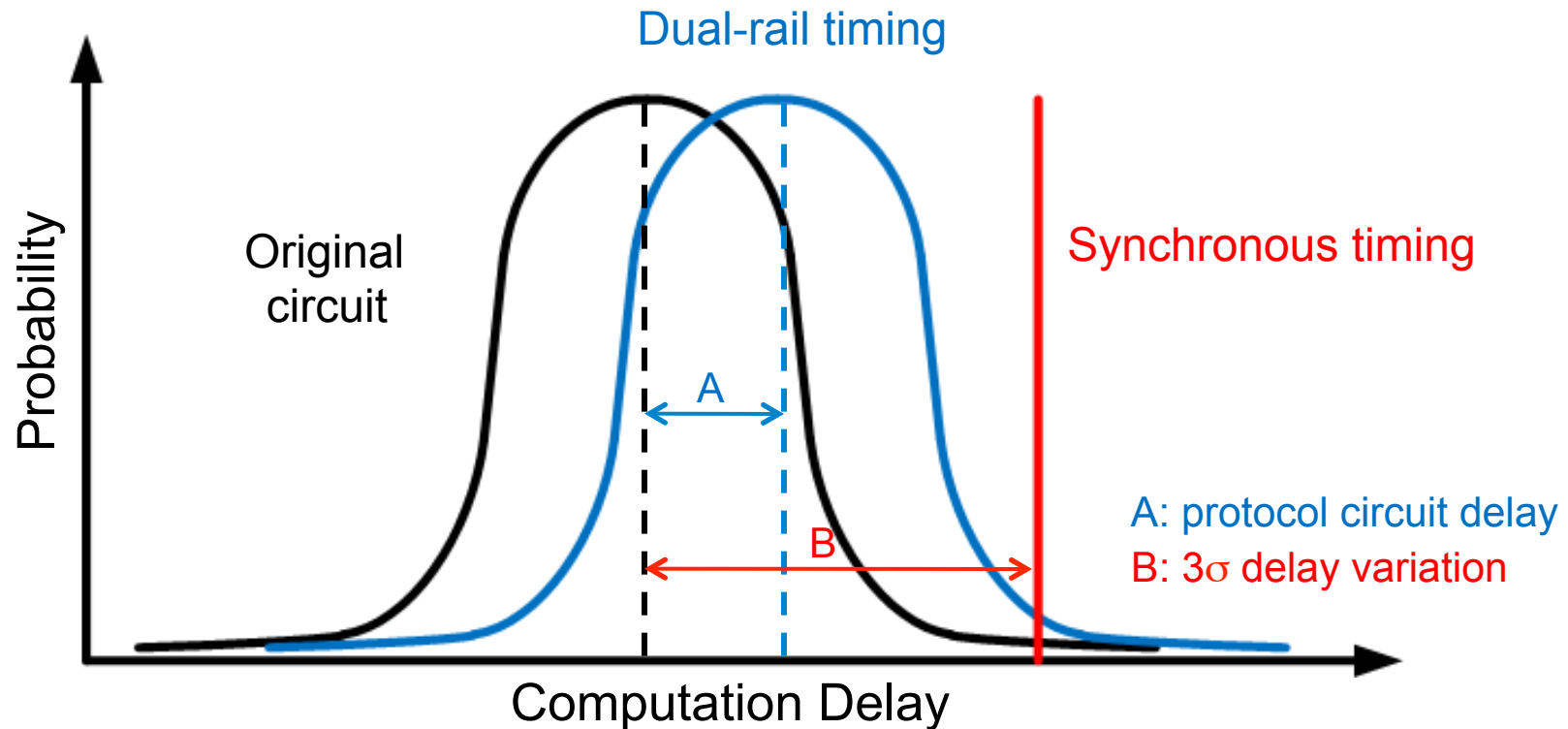
$$\frac{\sigma_{T_d, total_n}}{\mu_{T_d, total_n}} = \sqrt{\left(\frac{\sigma_{T_d, DTD_4}}{\mu_{T_d, DTD_4}}\right)^2 + \left(\frac{4}{n}\right) \cdot \left(\frac{\sigma_{T_d, WID_4}}{\mu_{T_d, WID_4}}\right)^2}$$

- Use 4-stage inverter chain model as baseline model
- Model error <13% for $n=8$ and <15% for $n=24$

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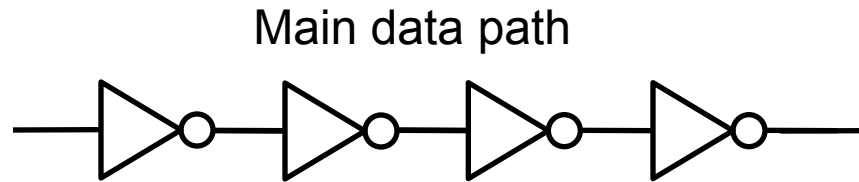
Delay Overhead Evaluation



- Assumption: Process variation follows Gaussian distribution
- Dual-rail approach: have only protocol overhead but no delay overhead
- Synchronous approach: have only delay overhead

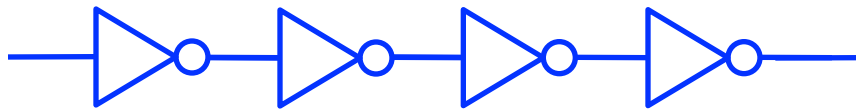
$$\text{For 99.7\% yield: } D_{sync} = \frac{3\sigma_{logic,total}}{\mu_{logic,total}}$$

Bundled-Data Self-Timed Approach

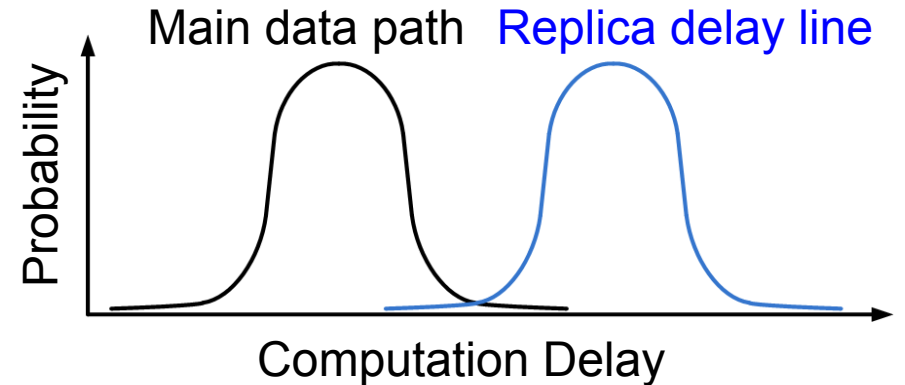


$$f_{logic}(t) = N(\mu_{logic}, \sigma_{logic}^2)$$

Replica delay line



$$f_{delay-line} = N(\mu_{delay-line}, \sigma_{delay-line}^2)$$



$$\text{Goal: } P(t_{logic} \leq t_{delay-line}) \approx 1$$

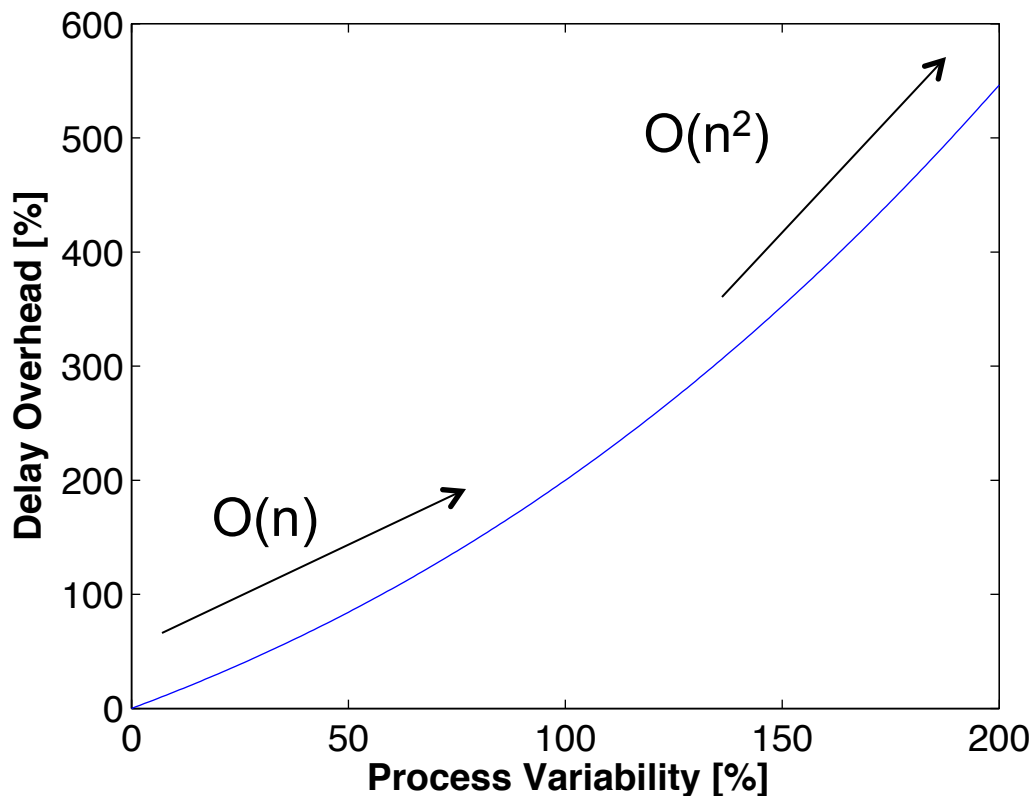
Assume main data path and replica delay line exhibit similar statistics:

$$\text{For 99.7\% yield: } D_{bundled-data} = D_{variation}^2 \cdot \left(0.5 + \sqrt{0.25 + \frac{2}{D_{variation}^2}} \right)$$

$$\text{where } D_{bundled-data} = \frac{\mu_{delay-line} - \mu_{logic}}{\mu_{logic}} \quad D_{variation} = \frac{3\sigma_{logic,WID}}{\mu_{logic,WID}}$$

Bundled-Data Delay Overhead

$$D_{\text{bundled-data}} \propto \begin{cases} \sqrt{2} \cdot D_{\text{variation}}, & \text{when } D_{\text{variation}} \rightarrow 0 \\ D_{\text{variation}}^2, & \text{when } D_{\text{variation}} \rightarrow \infty \end{cases}.$$



- Delay overhead becomes much larger as process variability increases!

Performance Model under Variations

Original delay and energy model

$$T_{\text{comp}} = T_{\text{delay}}$$

$$E_{\text{dynamic}} = \alpha C_{\text{switch}} V^2$$

$$E_{\text{leakage}} = V I_{\text{leakage}} T_{\text{delay}}$$

$$E_{\text{total}} = \alpha C_{\text{switch}} V^2 + V I_{\text{leakage}} T_{\text{delay}}$$

Statistical delay and energy model

$$T_{\text{comp}} = T_{\text{delay}} (1 + P + D)$$

$$E_{\text{dynamic}} = \alpha C_{\text{switch}} (1 + P) V^2$$

$$E_{\text{leakage}} = V I_{\text{leakage}} (1 + P) T_{\text{delay}} (1 + P + D)$$

$$E_{\text{total}} = \alpha C_{\text{switch}} (1 + P) V^2 + V I_{\text{leakage}} (1 + P) T_{\text{delay}} (1 + P + D)$$

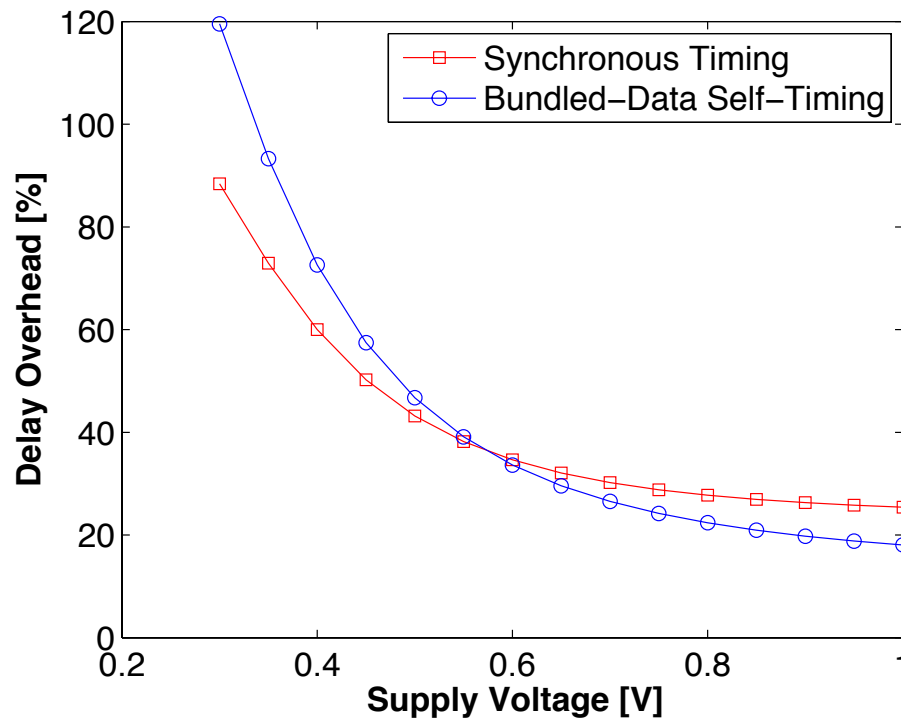
Timing scheme	Synchronous	Bundled-Data	Dual-Rail
Delay Overhead (D)	D_{sync}	$D_{\text{bundled-data}}$	0
Protocol Overhead (P)	0	$P_{\text{bundled-data}}$	$P_{\text{dual-rail}}$

- Evaluate computation delay and energy under variations
- Overhead changes with supply voltage and logic depth

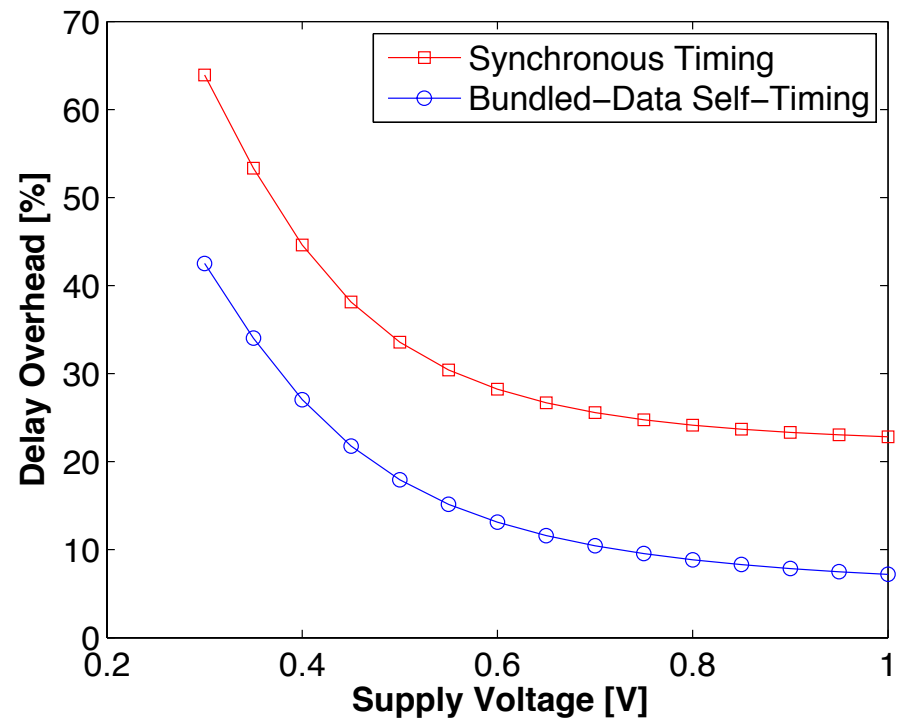
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Delay Overhead Comparison



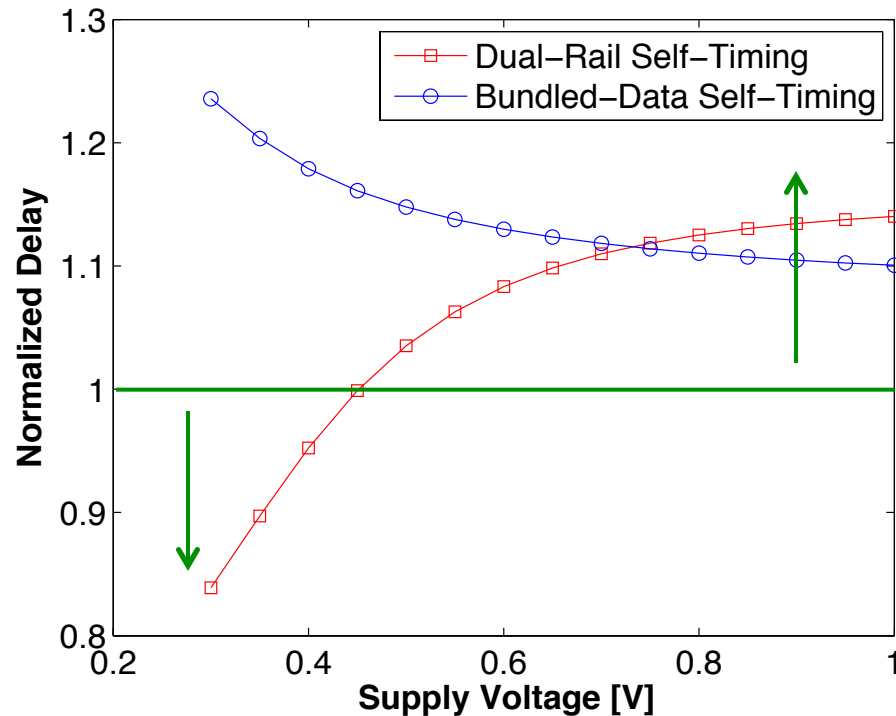
4-stage FO4 INV chain



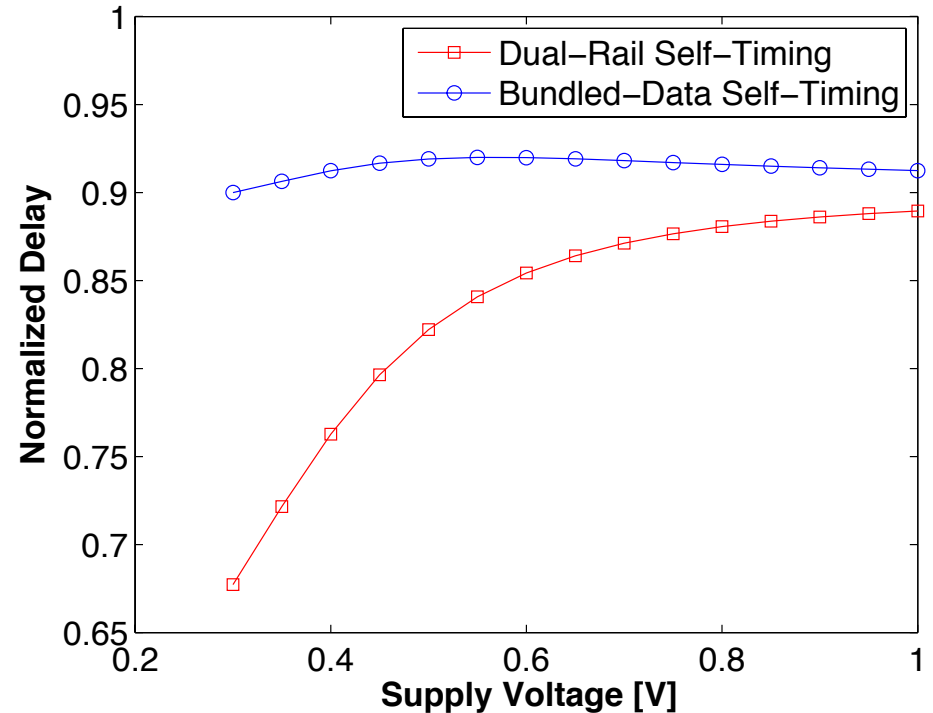
24-stage FO4 INV chain

- Global variation affects only synchronous approach
- Local mismatch dominates at low supply voltages
- Local mismatch has less impact on longer critical path

Speed Performance Comparison



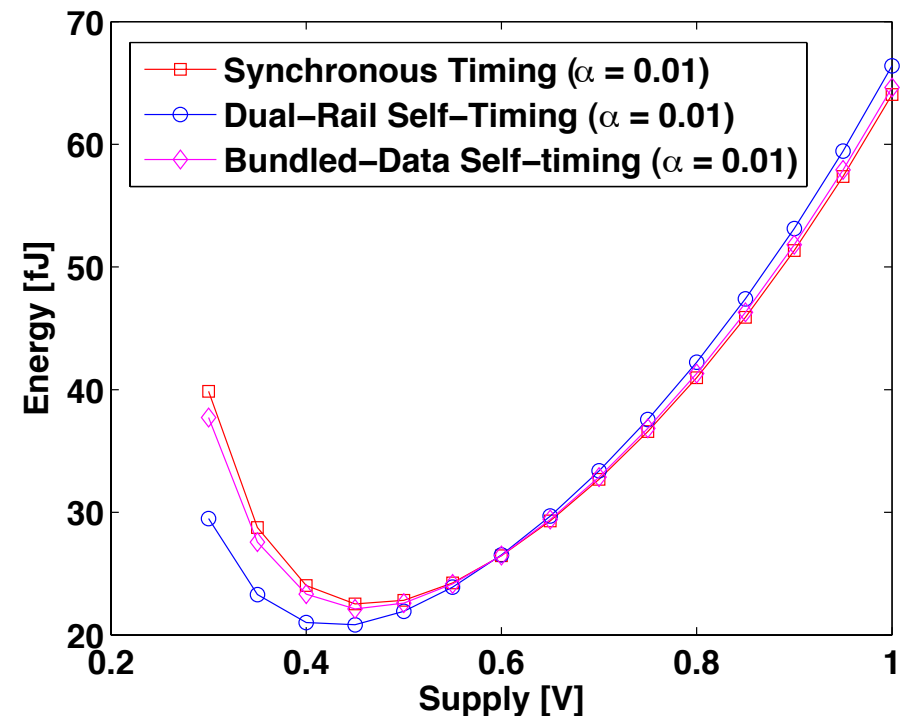
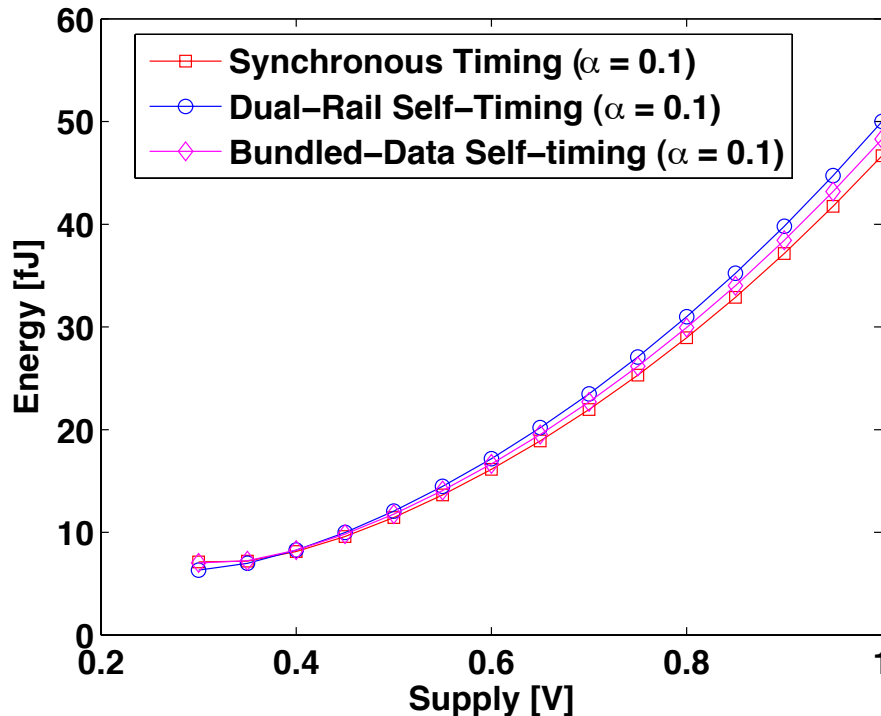
4-stage FO4 INV chain



24-stage FO4 INV chain

- Assumption: $P_{\text{bundled-data}} = 1T_{\text{FO4}}$; $P_{\text{dual-rail}} = 2T_{\text{FO4}}$
- Synchronous scheme is better for small critical path at high supply voltages
- Dual-rail scheme is better for large critical path at low supply voltages

Energy Performance Comparison



24-stage FO4 INV chain

- Synchronous scheme is better for high activity at high supply voltages
- Dual-rail scheme is better for low activity at low supply voltages
- Leakage dominates for low activity at low supply voltages

Conclusion

- A statistical analysis framework is proposed to evaluate performance of CMOS digital circuit in the presence of process variations.
- Designer can efficiently determine the optimal timing strategy, pipeline depth and supply voltage based on the proposed variability and statistical performance models.
- Asynchronous design exhibits better energy and delay characteristics for circuits with low activity and larger critical path delay under process variations

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Thank you!